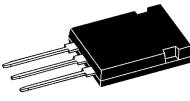


Contents

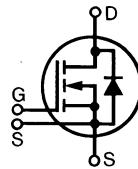
V_{DSS} max V	I_{D25} $T_c =$ 25 °C A	$R_{DS(on)}$ mΩ	miniBLOC 	ISOPLUS247™ 	Page
600	40	70	IXKN 40N60C		C5-2
	40	70		IXKR 40N60	C5-4
	75	35	IXKN 75N60		C5-6

CoolMOS is a trademark of Infineon Technologies AG.

CoolMOS Power MOSFET**IXKN 40N60C**

N-Channel Enhancement Mode
Low $R_{DS(on)}$, High V_{DSS} MOSFET

V_{DSS}	I_{D25}	$R_{DS(on)}$
600 V	40 A	70 mΩ


COOLMOS
Power Semiconductors

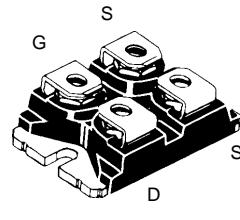
Symbol	Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	600	V
V_{GS}		± 20	V
I_{D25}	$T_C = 25^\circ\text{C}$	40	A
I_{D90}	$T_C = 90^\circ\text{C}$	27	A
E_{AR}	$I_D = 20 \text{ A}, L = 5 \mu\text{H}, T_{VJ} = 25^\circ\text{C}$, repetitive	1	mJ
E_{AS}	$I_D = 10 \text{ A}, L = 36 \text{ mH}, T_{VJ} = 25^\circ\text{C}$, non repetitive	1.8	J
dv/dt	$V_{DS} \leq V_{DSS}, I_S = 47 \text{ A}, dv/dt = 100 \text{ A}/\mu\text{s}, T_J = T_{JM}$	6	V/ns
P_D	$T_C = 25^\circ\text{C}$	290	W
T_J		-40 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-40 ... +150	$^\circ\text{C}$
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	2500	V
M_d	Mounting torque Terminal connection torque (M4)	1.5/13	Nm/lb.in. 1.5/13 Nm/lb.in.

MOSFET

Symbol	Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
V_{DSS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	600		V
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$ $V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	0.5 50	25 μA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}, I_D = 0.5 \cdot I_{D25}$			70 mΩ
$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 2.5 \text{ mA}$	3.5		5.5 V
I_{GSS}	$V_{GS} = \pm 20 \text{ V}_DC, V_{DS} = 0$			$\pm 100 \text{ nA}$

miniBLOC, SOT-227 B

E72873



G = Gate
S = Source
D = Drain

Either source terminal at miniBLOC can be used as main or kelvin source

Features

- miniBLOC package
 - Electrically isolated copper base
 - Low coupling capacitance to the heatsink for reduced EMI
 - High power dissipation due to AlN ceramic substrate
 - International standard package SOT-227
 - Easy screw assembly
- Fast CoolMOS power MOSFET
 - High blocking capability
 - Low on resistance
 - Avalanche rated for unclamped inductive switching (UIS)
 - Low thermal resistance due to reduced chip thickness
- Enhanced total power density

Applications

- Switched mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)
- Power factor correction (PFC)
- Welding
- Inductive heating

CoolMOS is a trademark of
Infineon Technologies AG.

Symbol	Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$	30	S	
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	8.8 3.15 36	nF nF pF	
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10 \text{ V}, V_{DS} = 350 \text{ V}, I_D = I_{D25}$	220 56 123	nC nC nC	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10 \text{ V}, V_{DS} = 350 \text{ V}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1.8 \Omega$ (External)	28 95 100 10	ns ns ns ns	
R_{thJC} R_{thCK}		0.05	0.43 K/W K/W	

Source-Drain Diode

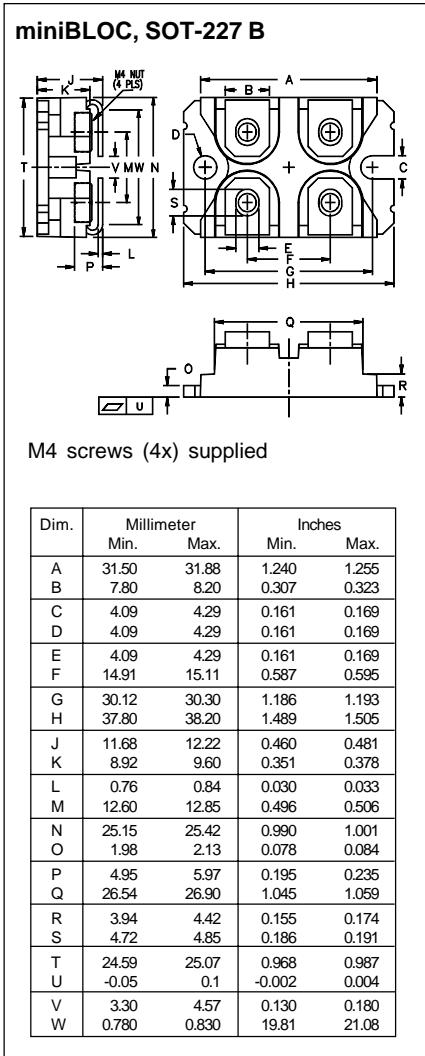
Characteristic Values
($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Conditions	min.	typ.	max.
V_{SD}	$I_F = 0.5 \cdot I_{D25}, V_{GS} = 0 \text{ V}$	0.9	1.1	V
t_{rr} I_{RM}	$I_F = 47 \text{ A}, -di/dt = 100 \text{ A}/\mu\text{s}$ $V_R = 350 \text{ V}, T_J = 125^\circ\text{C}$	650 110		ns A

Package

Characteristic Values

Symbol	Conditions	min.	typ.	max.
Weight		30		g

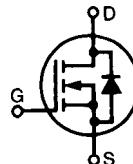


CoolMOS Power MOSFET

in ISOPLUS247™ Package

IXKR 40N60

N-Channel Enhancement Mode
 Low $R_{DS(on)}$, High V_{DSS} MOSFET
 Package with Electrically Isolated Base

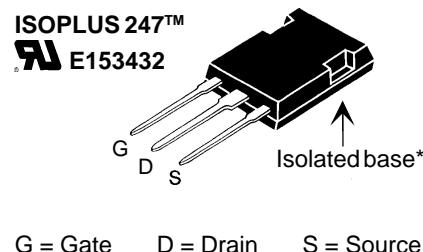

COOLMOS®
 Power Semiconductors

V_{DSS}	I_{D25}	$R_{DS(on)}$
600 V	40 A	70 mΩ

Symbol	Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	600	V	
V_{GS}		± 20	V	
I_{D25}	$T_C = 25^\circ\text{C}$	40	A	
I_{D90}	$T_C = 90^\circ\text{C}$	25	A	
I_{DM}	$T_C = 25^\circ\text{C}$, Pulse width limited by T_{JM}	160	A	
I_{AR}	$T_C = 25^\circ\text{C}$, $L = 1.6 \mu\text{H}$, single pulse	45	A	
E_{AS}		1.8	J	
dv/dt	$V_{DS} \leq V_{DSS}$, $I_S = 40 \text{ A}$, $dI_S/dt = 100 \text{ A}/\mu\text{s}$, $T_J = T_{JM}$	6	V/ns	
P_D	$T_C = 25^\circ\text{C}$	300	W	
T_J		-55 ... +150	°C	
T_{JM}		150	°C	
T_{stg}		-55 ... +150	°C	
T_L	1.6 mm (0.062 in.) from case for 10 s	300	°C	
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	2500	V~	

MOSFET

Symbol	Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
V_{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	600		V
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$ $V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	0.5 5	50 μA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$, $I_D = 0.5 \cdot I_{D25}$			70 mΩ
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 3 \text{ mA}$	3.5		5.5 V
I_{GSS}	$V_{GS} = \pm 20 \text{ V}_{DC}$, $V_{DS} = 0$			$\pm 100 \text{ nA}$



G = Gate D = Drain S = Source

* Patent pending

Features

- ISOPLUS247 package with DCB Base
 - Electrical isolation towards the heatsink
 - Low coupling capacitance to the heatsink for reduced EMI
 - High power dissipation
 - High temperature cycling capability of chip on DCB
 - JEDEC TO247AD compatible
 - Easy clip assembly
- CoolMOS power MOSFET
 - High blocking capability
 - Low on resistance
 - Avalanche rated for unclamped inductive switching (UIS)
 - Low thermal resistance due to reduced chip thickness
- Enhanced total power density

Applications

- Switched mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)
- Power factor correction (PFC)
- Welding
- Inductive heating

 CoolMOS is a trademark of
 Infineon Technologies AG.

Symbol	Conditions	Characteristic Values			
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.	max.
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$		30	S	
C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		7.8	nF	
C_{oss}			5	nF	
C_{rss}			260	pF	
$Q_{g(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 400 \text{ V}, I_D = I_{D25}$		260	nC	
Q_{gs}			50	nC	
Q_{gd}			130	nC	
$t_{d(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1.5 \Omega$ (External)		50	ns	
t_r			40	ns	
$t_{d(off)}$			100	ns	
t_f			20	ns	
R_{thJC}			0.42	K/W	
R_{thCK}			0.15	K/W	

Source-Drain Diode

Characteristic Values

 $(T_J = 25^\circ\text{C}, \text{unless otherwise specified})$

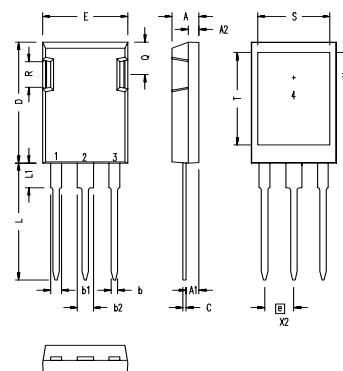
Symbol	Conditions	min.	typ.	max.
V_{SD}	$I_F = 0.5 \cdot I_{D25}, V_{GS} = 0 \text{ V}$		1.2	V
t_{rr}	$I_F = I_{D25}, -di/dt = 250 \text{ A}/\mu\text{s}, V_R = 350 \text{ V}, T_J = 125^\circ\text{C}$	600		ns
I_{RM}		10		A

Package

Characteristic Values

Symbol	Conditions	min.	typ.	max.
Weight		6		g

ISOPLUS 247 OUTLINE



1 Gate, 2 Drain (Collector)
3 Source (Emitter)
4 no connection

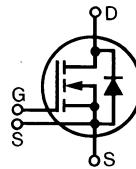
Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.83	5.21	.190	.205
A ₁	2.29	2.54	.090	.100
A ₂	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b ₁	1.91	2.13	.075	.084
b ₂	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45	BSC	.215	BSC
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	.244
R	4.32	4.83	.170	.190

CoolMOS Power MOSFET

IXKN 75N60

N-Channel Enhancement Mode
Low $R_{DS(on)}$, High V_{DSS} MOSFET

V_{DSS}	I_{D25}	$R_{DS(on)}$
600 V	75 A	35 mΩ

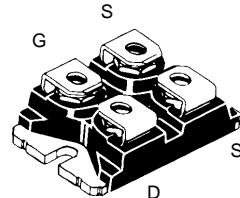


COOLMOS
Power Semiconductors

Symbol	Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	600	V	
V_{GS}		± 20	V	
I_{D25}	$T_C = 25^\circ\text{C}$	75	A	
I_{D90}	$T_C = 90^\circ\text{C}$	50	A	
I_{DM}	$T_C = 25^\circ\text{C}$, Pulse width limited by T_{JM}	300	A	
I_{AR}	$T_C = 25^\circ\text{C}$, $L = 1.6 \mu\text{H}$, single pulse	90	A	
E_{AS}		3.6	J	
dv/dt	$V_{DS} \leq V_{DSS}$, $I_S = 75 \text{ A}$, $dI_S/dt = 200 \text{ A}/\mu\text{s}$, $T_J = T_{JM}$	6	V/ns	
P_D	$T_C = 25^\circ\text{C}$	520	W	
T_J		-40 ... +150	°C	
T_{JM}		150	°C	
T_{stg}		-40 ... +150	°C	
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	2500	V~	
M_d	Mounting torque Terminal connection torque (M4)	1.5/13	Nm/lb.in.	
		1.5/13	Nm/lb.in.	

miniBLOC, SOT-227 B

E72873



G = Gate
S = Source
D = Drain

Either source terminal at miniBLOC can be used as main or kelvin source

Features

- miniBLOC package
 - Electrically isolated copper base
 - Low coupling capacitance to the heatsink for reduced EMI
 - High power dissipation due to AlN ceramic substrate
 - International standard package SOT-227
 - Easy screw assembly
- CoolMOS power MOSFET
 - High blocking capability
 - Low on resistance
 - Avalanche rated for unclamped inductive switching (UIS)
 - Low thermal resistance due to reduced chip thickness

- Enhanced total power density
- Applications

- Switched mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)
- Power factor correction (PFC)
- Welding
- Inductive heating

MOSFET Symbol

Conditions

Characteristic Values
($T_J = 25^\circ\text{C}$, unless otherwise specified)

		min.	typ.	max.
V_{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 1 \text{ mA}$	600		V
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$ $V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	1 10	100 μA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$, $I_D = 0.5 \cdot I_{D25}$			35 mΩ
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 5.5 \text{ mA}$	3.5		5.5 V
I_{GSS}	$V_{GS} = \pm 20 \text{ V}_{DC}$, $V_{DS} = 0$			$\pm 200 \text{ nA}$

CoolMOS is a trademark of
Infineon Technologies AG.

Symbol	Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$	60	S	
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	15.6 10 530	nF nF pF	
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10 \text{ V}, V_{DS} = 400 \text{ V}, I_D = I_{D25}$	520 100 260	nC nC nC	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1 \Omega$ (External)	50 40 100 20	ns ns ns ns	
R_{thJC} R_{thCK}		0.05	0.24 K/W K/W	

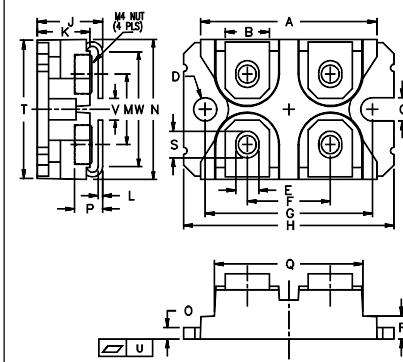
Source-Drain DiodeCharacteristic Values
($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Conditions	min.	typ.	max.
V_{SD}	$I_F = 0.5 \cdot I_{D25}, V_{GS} = 0 \text{ V}$		1.2	V
t_{rr} I_{RM}	$I_F = I_{D25}, -di/dt = 500 \text{ A}/\mu\text{s},$ $V_R = 350 \text{ V}, T_J = 125^\circ\text{C}$	600 20		ns A

Package

Characteristic Values

Symbol	Conditions	min.	typ.	max.
Weight		30		g

miniBLOC, SOT-227 B

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	37.80	38.20	1.489	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.76	0.84	0.030	0.033
M	12.60	12.85	0.496	0.506
N	25.15	25.42	0.990	1.001
O	1.98	2.13	0.078	0.084
P	4.95	5.97	0.195	0.235
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.174
S	4.72	4.85	0.186	0.191
T	24.59	25.07	0.968	0.987
U	-0.05	0.1	-0.002	0.004
V	3.30	4.57	0.130	0.180
W	0.780	0.830	19.81	21.08

